PATENT ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Applied Materials, Inc.	05/12/2011

RECEIVING PARTY DATA

Name:	Quantum Global Technologies LLC
Street Address:	123 N. Main Street
City:	Dublin
State/Country:	PENNSYLVANIA
Postal Code:	18917

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13157867

OP $40.00 13157867

CORRESPONDENCE DATA

Fax Number: (609)896-1469
Phone: 609.844.3020
Email: ipdocket@foxrothschild.com, cwray@foxrothschild.com
Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.
Correspondent Name: FOX ROTHSCHILD LLP
Address Line 1: IP DOCKET, PO BOX 5231
Address Line 4: LAWRENCEVILLE, NEW JERSEY 08543-5231

ATTORNEY DOCKET NUMBER:	069918.00005
NAME OF SUBMITTER:	Carol Wray

Total Attachments: 10
source=Assigment#page1.tif
source=Assigment#page2.tif
source=Assigment#page3.tif
source=Assigment#page4.tif

source=Assigment#page5.tif
source=Assigment#page6.tif
source=Assigment#page7.tif
source=Assigment#page8.tif
source=Assigment#page9.tif
source=Assigment#page10.tif

ASSIGNMENT OF PATENTS AND PATENT APPLICATIONS

THIS ASSIGNMENT OF PATENTS AND PATENT APPLICATIONS ("Assignment"), is effective as of the date of closing, the 12th day of May, 2011 (the "Effective Date") and is by and between Applied Materials, Inc., a Delaware corporation ("Assignor") having a principal place of business at 3050 Bowers Avenue, Santa Clara, CA 95054 USA, and Quantum Global Technologies LLC, a Delaware limited liability company ("Assignee") and having a principal place of business at 123 N. Main Street Dublin, PA 18917 USA. Capitalized terms used but not defined herein shall have the meanings ascribed to such terms in the Asset Purchase Agreement (the "Asset Purchase Agreement") dated as of April 4, 2011 by and between Applied Materials, Inc. and Quantum Global Technologies LLC.

RECITALS

A. Assignor is the owner of certain patents and patent applications identified in Schedule A attached hereto (the "Patent Rights"); and

B. Pursuant to the Asset Purchase Agreement, Assignor has agreed to sell, assign, transfer and deliver all of the Patent Rights unto Assignee.

NOW, THEREFORE, in consideration of the Purchase Price set forth in the Asset Purchase Agreement (which Purchase Price is allocated in the manner set forth in Section 1.3 thereof) and for good and valuable consideration, the receipt, sufficiency and adequacy of which are hereby acknowledged, Assignor does hereby sell, assign and transfer unto the Assignee, its successors and assigns, effective as of the Effective Date, the entire and exclusive right, title and interest in and to the Patent Rights, including, but not limited to, all rights, title and interest in and to all inventions disclosed or claimed therein, throughout the world (with priority rights), and in and to any conversions, continuations, continuations-in-part, divisions, reissues, re-examinations, extensions and foreign counterparts , and including, without limitation, all claims for damages by reason of past infringement, with the right to sue for and collect the same.

Assignor agrees, without further consideration, to execute (and to use all commercially reasonable efforts to cause its employees and consultants to execute), upon request by Assignee, all oaths, assignments, powers of attorney, applications, and other papers necessary or desirable to fully secure to Assignee the right, title and interest conveyed herein, and to take such further actions as may be reasonably requested by Assignee in order to carry out the provisions and purposes of this Assignment including, without limitation, to execute one or more further assignments covering the Patent Rights in a form acceptable for recordation in domestic and foreign patent offices worldwide; *provided, however*, that with respect to any oath, assignment, power of attorney, application or other paper required to be executed hereunder from and after the date that that is ninety (90) days following the date hereof, Assignee shall endeavor to provide Assignor with the same not less than one month prior to the date such paper is required to be delivered by Assignee to a third party, or filed with a governmental authority, as applicable. Appropriate government agencies, including the Commissioner of Patents of the United States of America, are hereby authorized and requested to issue said letters patents to Assignee, in accordance with this assignment.

IN WITNESS WHEREOF, Assignor and Assignee have caused this Assignment of Patents and Patent Applications to be executed as of the last date set forth below.

Applied Materials Inc.

By:_____
Name:
Title:

Date: _____, 2011

STATE OF)
) ss:
COUNTY OF)

On the ____ day of May in the year 2011 before me, the undersigned, a notary public in and for said state, personally appeared _____, personally known to me or proved to me on the basis of satisfactory evidence to be the individual whose name is subscribed to the within instrument, and acknowledged to me that he executed the same in his capacity, and that by his signature on the instrument, the individual, or the person upon behalf of whom the individual acted, executed the instrument.

_____
Notary Public

Quantum Global Technologies LLC

By: Scott H. Nicholas
Name: Scott H. Nicholas
Title: President

Date: May 12th, 2011

STATE OF Pennsylvania)
) ss:
COUNTY OF Bucks)

On the 12th day of May in the year 2011 before me, the undersigned, a notary public in and for said state, personally appeared Scott H. Nicholas, personally known to me or proved to me on the basis of satisfactory evidence to be the individual whose name is subscribed to the within instrument, and acknowledged to me that he executed the same in his capacity, and that by his signature on the instrument, the individual, or the person upon behalf of whom the individual acted, executed the instrument.

Joanne R Focht
Notary Public

NOTARIAL SEAL
JOANNE R FOCHT
Notary Public
WARRINGTON TWP,BUCKS CNTY
My Commission Expires Oct 23, 2013

IN WITNESS WHEREOF, Assignor and Assignee have caused this Assignment of Patents and Patent Applications to be executed as of the last date set forth below.

Applied Materials Inc.

By: _____
Name:
Title:

Date: May 12, 2011

STATE OF)
) ss:
COUNTY OF)

On the 12th day of May in the year 2011 before me, the undersigned, a notary public in and for said state, personally appeared Cassio Conceicao, personally known to me or proved to me on the basis of satisfactory evidence to be the individual whose name is subscribed to the within instrument, and acknowledged to me that he executed the same in his capacity, and that by his signature on the instrument, the individual, or the person upon behalf of whom the individual acted, executed the instrument.

TRANG T. CHAU
Commission # 1888927
Notary Public - California
Santa Clara County
My Comm. Expires May 10, 2014

_____
Notary Public

Quantum Global Technologies LLC

By: _____
Name:
Title:

Date: _____, 2011

STATE OF)
) ss:
COUNTY OF)

On the _____ day of May in the year 2011 before me, the undersigned, a notary public in and for said state, personally appeared _____, personally known to me or proved to me on the basis of satisfactory evidence to be the individual whose name is subscribed to the within instrument, and acknowledged to me that he executed the same in his capacity, and that by his signature on the instrument, the individual, or the person upon behalf of whom the individual acted, executed the instrument.

_____
Notary Public

CALIFORNIA ALL-PURPOSE ACKNOWLEDGMENT

State of California

County of Santa Clara

On May 12, 2011 (Date) before me, Trang T. Chau Notary Public (Here Insert Name and Title of the Officer),

personally appeared Cassio Conceicao (Name(s) of Signer(s))

who proved to me on the basis of satisfactory evidence to be the person(s) whose name(s) is/~~are~~ subscribed to the within instrument and acknowledged to me that he/~~she~~/~~they~~ executed the same in his/~~her~~/~~their~~ authorized capacity~~(ies)~~, and that by his/~~her~~/~~their~~ signature~~(s)~~ on the instrument the person(s), or the entity upon behalf of which the person(s) acted, executed the instrument.

I certify under PENALTY OF PERJURY under the laws of the State of California that the foregoing paragraph is true and correct.

WITNESS my hand and official seal.

TRANG T. CHAU
Commission # 1888927
Notary Public - California
Santa Clara County
My Comm. Expires May 10, 2014

Place Notary Seal Above

Signature: Trang T. Chau (Signature of Notary Public)

OPTIONAL

Though the information below is not required by law, it may prove valuable to persons relying on the document and could prevent fraudulent removal and reattachment of this form to another document.

Description of Attached Document

Title or Type of Document: ~~Assignment~~ Trademark, Assignment of Patents

Document Date: May 12, 2011 Number of Pages: #8

Signer(s) Other Than Named Above: _____

Capacity(ies) Claimed by Signer(s)

Signer's Name: Cassio Conceicao	Signer's Name: _____
☒ Corporate Officer — Title(s): VP + GM	☐ Corporate Officer — Title(s): _____
☐ Individual	☐ Individual
☐ Partner — ☐ Limited ☐ General	☐ Partner — ☐ Limited ☐ General
☐ Attorney in Fact	☐ Attorney in Fact
☐ Trustee	☐ Trustee
☐ Guardian or Conservator	☐ Guardian or Conservator
☐ Other: _____	☐ Other: _____
Signer Is Representing: _____	Signer Is Representing: _____
RIGHT THUMBPRINT OF SIGNER — Top of thumb here	RIGHT THUMBPRINT OF SIGNER — Top of thumb here

SCHEDULE A

PATENT RIGHTS

Dkt No		Application No	File Dt	Nat'l File Dt	Patent No	Grnt Dt	Publication No	Pub Dt	Title
010218JAPAP	JAPAN	2009-535302	10/31/2007	5/1/2009					METHODS AND APPARATUS FOR CLEANING CHAMBER COMPONENTS
010218KORSP	KOREA	7011331/09	10/31/2007	6/1/2009			91153/09	8/26/2009	METHODS AND APPARATUS FOR CLEANING CHAMBER COMPONENTS
010218SINGP	SINGAPORE	200902914-1	10/31/2007	4/29/2009					METHODS AND APPARATUS FOR CLEANING CHAMBER COMPONENTS
010218TAIW	TAIWAN	96141240.0	11/1/2007	11/1/2007			200833430	8/16/2008	METHODS AND APPARATUS FOR CLEANING CHAMBER COMPONENTS
010218USA	US	11/931,272	10/31/2007	10/31/2007	7789969		2008-0099054	5/1/2008	METHODS AND APPARATUS FOR CLEANING CHAMBER COMPONENTS
010891CHINP	CHINA	200480027643.X	7/23/2004	4/14/2006	200480027643.X	1/7/2009			ULTRASONIC ASSISTED ETCH USING CORROSIVE LIQUIDS
010891CHINP02	CHINA	200480027634.0	7/22/2004	3/24/2006			CN100449699	1/7/2009	CLEANING MASKS
010891JAPAP	JAPAN	2006-521293	7/23/2004	1/24/2006			2007-500431	1/11/2007	ULTRASONIC ASSISTED ETCH USING CORROSIVE LIQUIDS
010891JAPAP02	JAPAN	2006-521239	7/22/2004	1/24/2006			2006-528840	12/21/2006	CLEANING MASKS
010891JAPAPD01	JAPAN	2010-202226	7/22/2004	9/9/2010					CLEANING MASKS
010891KORSP	KOREA	7001651/06	7/23/2004	1/24/2006					ULTRASONIC ASSISTED ETCH USING CORROSIVE LIQUIDS
010891KORSP02	KOREA	7001627/06	7/22/2004	1/24/2006					CLEANING MASKS
010891TAIW	TAIWAN	93122253.0	7/26/2004	7/26/2004	244693	12/1/2005		12/1/2005	ULTRASONIC ASSISTED ETCH USING CORROSIVE LIQUIDS
010891TAIW02	TAIWAN	93122257.0	7/26/2004	7/26/2004	251855	3/21/2006		3/21/2006	CLEANING MASKS
010891USA	US	10/627,416	7/24/2003	7/24/2003	7091132	8/15/2006	2005-0016959	1/27/2005	ULTRASONIC ASSISTED ETCH USING CORROSIVE LIQUIDS
010891USAD01	US	11/477,191	6/27/2006	6/27/2006	7377991	5/27/2008	2006-0248890	11/2/2006	ULTRASONIC ASSISTED ETCH USING CORROSIVE LIQUIDS
010891SINGP	SINGAPORE	200600492-3	7/23/2004						ULTRASONIC ASSISTED ETCH USING CORROSIVE LIQUIDS
010891SINGP02D2	SINGAPORE	200805492-6	7/22/2004						CLEANING MASKS
010891SINGPD01	SINGAPORE	200805491-9	7/23/2004						ULTRASONIC ASSISTED ETCH USING CORROSIVE LIQUIDS
010892USA	US	10/696,394	10/28/2003	10/28/2003	7754609	7/13/2010			CLEANING PROCESS FOR SILICON CARBIDE MATERIALS
010893CHINP	CHINA	200480027645.9	7/22/2004	3/24/2006					CLEANING PROCESS AND APPARATUS FOR SILICATE MATERIALS
010893CHINPD01	CHINA	201010151738.X	7/22/2004						CLEANING PROCESS AND APPARATUS FOR SILICATE MATERIALS
010893SINGP	SINGAPORE	200600493-1	7/22/2004						CLEANING PROCESS AND APPARATUS FOR SILICATE MATERIALS
010893SINGPD01	SINGAPORE	200805490-0	7/22/2004						CLEANING PROCESS AND APPARATUS FOR SILICATE MATERIALS
010893JAPAP	JAPAN	2006-521240	7/22/2004	1/24/2006			2006-528841	12/21/2006	CLEANING PROCESS AND APPARATUS FOR SILICATE MATERIALS
010893KORSP	KOREA	7001653/06	7/22/2004	1/24/2006					CLEANING PROCESS AND APPARATUS FOR SILICATE MATERIALS

Dkt No		Application No	File Dt	Nat'l File Dt	Patent No	Grnt Dt	Publication No	Pub Dt	Title
010893TAIW	TAIWAN	93122255.0	7/26/2004	7/26/2004	251873	3/21/2006		3/21/2006	CLEANING PROCESS AND APPARATUS FOR SILICATE MATERIALS
010893USA	US	10/627,185	7/24/2003	7/24/2003	7045072	5/16/2006	2005-0016958	1/27/2005	CLEANING PROCESS AND APPARATUS FOR SILICATE MATERIALS
010893USAD01	US	11/061,013	2/17/2005	2/17/2005	7452475	11/18/2008	2005-0167393	8/4/2005	CLEANING PROCESS AND APPARATUS FOR SILICATE MATERIALS
012260CHIN	CHINA	200810126036.9	6/30/2008	6/30/2008			CN101342534	1/14/2009	TANTALUM/TANTALUM NITRIDE STRIPPING OF CHAMBER PARTS USING SELECTIVE SPRAY ETCH
012260EPCE	EP	8159251.1	6/28/2008	6/28/2008			2011897	3/4/2009	TANTALUM/TANTALUM NITRIDE STRIPPING OF CHAMBER PARTS USING SELECTIVE SPRAY ETCH
012260JAPA	JAPAN	2008-169157	6/27/2008	6/27/2008			2009-007674	1/15/2009	TANTALUM/TANTALUM NITRIDE STRIPPING OF CHAMBER PARTS USING SELECTIVE SPRAY ETCH
012260KORS	KOREA	61871/08	6/28/2008	6/28/2008	1027612		4598/09	1/12/2009	METHODS AND APPARATUS FOR CLEANING DEPOSITION CHAMBER PARTS USING SELECTIVE SPRAY ETCH
012260SING	SINGAPORE	200804886-0	6/27/2008	6/27/2008			148875	1/29/2009	TANTALUM/TANTALUM NITRIDE STRIPPING OF CHAMBER PARTS USING SELECTIVE SPRAY ETCH
012260TAIW	TAIWAN	97123962.0	6/26/2008	6/26/2008			200908135	2/16/2009	TANTALUM/TANTALUM NITRIDE STRIPPING OF CHAMBER PARTS USING SELECTIVE SPRAY ETCH
012260USA	US	12/146,676	6/26/2008	6/26/2008			2009-0000641	1/1/2009	METHOD AND APPARATUS FOR CLEANING DEPOSITION CHAMBER PARTS USING SELECTIVE SPRAY ETCH
012632JAPAP	JAPAN	2010519987.0	8/9/2008	2/5/2010					METHOD AND APPARATUS FOR EX SITU SEASONING OF ELECTRONIC DEVICE MANUFACTURING PROCESS COMPONENTS
012632KORSP	KOREA	7005217/10	8/9/2008	3/9/2010					METHOD AND APPARATUS FOR EX SITU SEASONING OF ELECTRONIC DEVICE MANUFACTURING PROCESS COMPONENTS
012632SINGP	SINGAPORE	201000534-6	8/9/2008	2/10/2010					METHOD AND APPARATUS FOR EX SITU SEASONING OF ELECTRONIC DEVICE MANUFACTURING PROCESS COMPONENTS
012632TAIW	TAIWAN	97130580.0	8/11/2008	8/11/2008			200917332	4/16/2009	METHOD AND APPARATUS FOR EX SITU SEASONING OF ELECTRONIC DEVICE MANUFACTURING PROCESS COMPONENTS
012632USA	US	12/189,141	8/9/2008	8/9/2008			2009-0043416	2/12/2009	METHOD AND APPARATUS FOR EX SITU SEASONING OF ELECTRONIC DEVICE MANUFACTURING PROCESS COMPONENTS
013015PCTP	PCT	US08/87551	12/18/2008	12/18/2008			WO09/086023	10/1/2009	METHODS FOR CLEANING PROCESS KITS AND CHAMBERS AND FOR RUTHENIUM RECOVERY
013015JAPAP	JAPAN	2010539839	12/18/2008	6/19/2010					METHODS FOR CLEANING PROCESS KITS AND CHAMBERS AND FOR RUTHENIUM RECOVERY
013015KORSP	KOREA	7015752/10	12/18/2008	7/15/2010					METHODS FOR CLEANING PROCESS KITS AND CHAMBERS AND FOR RUTHENIUM RECOVERY
013015TAIW	TAIWAN	97149770.0	12/19/2008	12/19/2008			200943399	10/16/2009	METHODS FOR CLEANING PROCESS KITS AND CHAMBERS AND FOR RUTHENIUM RECOVERY
013015USA	US	12/339,037	12/18/2008	12/18/2008			2009-0197004	8/6/2009	METHODS FOR CLEANING PROCESS KITS AND CHAMBERS AND FOR RUTHENIUM RECOVERY
013097CHIN	CHINA	200410064239.1	8/19/2004	8/19/2004			CN1598061	3/23/2005	METHOD FOR REMOVING A COMPOSITE COATING CONTAINING TANTALUM DEPOSITION AND ARC SPRAYED ALUMINUM FROM CERAMIC SUBSTRATES
013097EPCE	EP	4254708.3	8/5/2004	8/5/2004	1508629	12/30/2009	1508629	3/23/2005	METHOD FOR REMOVING A COMPOSITE COATING CONTAINING TANTALUM DEPOSITION AND ARC SPRAYED ALUMINUM FROM CERAMIC SUBSTRATES
013097FRANCE	FRANCE	4254708.3	8/5/2004	8/5/2004	1508629	12/30/2009	1508629	3/23/2005	METHOD FOR REMOVING A COMPOSITE COATING CONTAINING TANTALUM DEPOSITION AND ARC SPRAYED ALUMINUM FROM CERAMIC SUBSTRATES

Dkt No		Application No	File Dt	Nat'l File Dt	Patent No	Grnt Dt	Publication No	Pub Dt	Title
013097GERWE	GERMANY	4254708.3	8/5/2004	8/5/2004	6002004024850	12/30/2009	1508629	3/23/2005	METHOD FOR REMOVING A COMPOSITE COATING CONTAINING TANTALUM DEPOSITION AND ARC SPRAYED ALUMINUM FROM CERAMIC SUBSTRATES
013097TAIW	TAIWAN	93124999.0	8/19/2004	8/19/2004			200522191	7/1/2005	METHOD FOR REMOVING A COMPOSITE COATING CONTAINING TANTALUM DEPOSITION AND ARC SPRAYED ALUMINUM FROM CERAMIC SUBSTRATES
013097USA	US	10/643,409	8/19/2003	8/19/2003	7097713	8/29/2006	2005-0039774	2/24/2005	METHOD FOR REMOVING A COMPOSITE COATING CONTAINING TANTALUM DEPOSITION AND ARC SPRAYED ALUMINUM FROM CERAMIC SUBSTRATES
013098CHINP	CHINA	200580008886.3	3/17/2005	9/15/2006			CN101304815	11/12/2008	PROCESS FOR PRODUCING SEMICONDUCTOR COATED SUBSTRATE
013098ISRAP	ISRAEL	178084.0	3/17/2005	9/14/2006					PROCESS FOR PRODUCING SEMICONDUCTOR COATED SUBSTRATE
013098JAPAP	JAPAN	2007-505028	3/17/2005	9/14/2006					PROCESS FOR PRODUCING SEMICONDUCTOR COATED SUBSTRATE
013098KORS	KOREA	5915/05	1/21/2005	1/21/2005					PROCESS FOR PRODUCING SEMICONDUCTOR COATED SUBSTRATE
013098SINGP	SINGAPORE	200606183-2	3/17/2005	9/14/2006	125478	9/30/2009			PROCESS FOR PRODUCING SEMICONDUCTOR COATED SUBSTRATE
013098TAIW	TAIWAN	93141280.0	12/30/2004	12/30/2004					PROCESS FOR PRODUCING SEMICONDUCTOR COATED SUBSTRATE
013098USA	US	10/807,716	3/24/2004	3/24/2004			2005-0215059	9/29/2005	PROCESS FOR PRODUCING SEMICONDUCTOR COATED SUBSTRATE
013101CHIN	CHINA	200610108616.6	7/28/2006	7/28/2006			CN1904124	1/31/2007	METHODS AND APPARATUS FOR THE APPLICATION OF TWIN WIRE ARC SPRAY COATINGS
013101EPCE	EP	6253692.5	7/14/2006	7/14/2006			1749899	7/2/2007	METHODS AND APPARATUS FOR THE APPLICATION OF TWIN WIRE ARC SPRAY COATINGS
013101JAPA	JAPAN	2006-206196	7/28/2006	7/28/2006			2007-105721	4/26/2007	METHODS AND APPARATUS FOR THE APPLICATION OF TWIN WIRE ARC SPRAY COATINGS
013101KORS	KOREA	7000930/06	7/27/2006	7/27/2006					METHODS AND APPARATUS FOR THE APPLICATION OF TWIN WIRE ARC SPRAY COATINGS
013101SING	SINGAPORE	200604845-8	7/20/2006	7/20/2006	128408	5/29/2009			METHODS AND APPARATUS FOR THE APPLICATION OF TWIN WIRE ARC SPRAY COATINGS
013101TAIW	TAIWAN	95127610.0	7/28/2006	7/28/2006					METHODS AND APPARATUS FOR THE APPLICATION OF TWIN WIRE ARC SPRAY COATINGS
013101USA	US	11/192,600	7/29/2005	7/29/2005	7554052	6/30/2009	2007-0026159	2/1/2007	METHODS AND APPARATUS FOR THE APPLICATION OF TWIN WIRE ARC SPRAY COATINGS
013102CHIN	CHINA	200610146482.7	11/13/2006	11/13/2006			CN1970230	5/30/2007	APPARATUS AND METHODS FOR SLURRY CLEANING OF ETCH CHAMBERS
013102EPCE	EP	6255599.0	10/31/2006	10/31/2006			1785230	5/16/2007	APPARATUS AND METHODS FOR SLURRY CLEANING OF ETCH CHAMBERS
013102FRANE	FRANCE	6255599	10/31/2006	1785230	1785230	4/21/2010			APPARATUS AND METHODS FOR SLURRY CLEANING OF ETCH CHAMBERS
013102GERWE	GERMANY	6255599.0	10/31/2006	1785230	602006013768	4/21/2010			APPARATUS AND METHODS FOR SLURRY CLEANING OF ETCH CHAMBERS
013102ISRA	ISRAEL	178946.0	10/31/2006	10/31/2006					APPARATUS AND METHODS FOR SLURRY CLEANING OF ETCH CHAMBERS
013102JAPA	JAPAN	2006-307392	11/14/2006	11/14/2006			2007-173785	7/5/2007	APPARATUS AND METHODS FOR SLURRY CLEANING OF ETCH CHAMBERS
013102KORS	KOREA	111696/06	11/13/2006	11/13/2006					APPARATUS AND METHODS FOR SLURRY CLEANING OF ETCH CHAMBERS
013102SING	SINGAPORE	200607533-7	11/2/2006	11/2/2006	132602	5/29/2009			APPARATUS AND METHODS FOR SLURRY CLEANING OF ETCH CHAMBERS

Dkt No		Application No	File Dt	Nat'l File Dt	Patent No	Grnt Dt	Publication No	Pub Dt	Title
013102TAIW	TAIWAN	95141986.0	11/14/2006	11/14/2006			200725733	7/1/2007	APPARATUS AND METHODS FOR SLURRY CLEANING OF ETCH CHAMBERS
013102USA	US	11/272,844	11/14/2005	11/14/2005			2007-0111642	5/17/2007	APPARATUS AND METHODS FOR SLURRY CLEANING OF ETCH CHAMBERS
013610USA	US	08/511,975	8/7/1995	8/7/1995	5651797	7/29/1997			APPARATUS AND METHOD FOR THE IMMERSION CLEANING AND TRANSPORT OF SEMICONDUCTOR COMPONENTS
013611USA	US	08/491,154	6/16/1995	6/16/1995	5660640	8/26/1997			METHOD FOR REMOVING SPUTTER DEPOSITION FRO COMPONENTS OF VACUUM DEPOSITION EQUIPMENT
014726PCTP	PCT	US10/48732	9/14/2010	9/14/2010					METHOD AND APPARATUS FOR SHOWERHEAD CLEANING
014726TAIW	TAIWAN	99131264	9/15/2010	9/15/2010					METHOD AND APPARATUS FOR SHOWERHEAD CLEANING
014726USA	US	12/881,503	9/14/2010	9/14/2010					METHOD AND APPARATUS FOR SHOWERHEAD CLEANING
008061CHINP	CHINA	200380106546.5	11/25/2002	6/17/2005	200380106546.5	5/5/2010			METHOD OF CLEANING A COATED PROCESS CHAMBER COMPONENT
008061JAPAP02	JAPAN	2006-545314	12/19/2003	6/19/2006					CLEANING TANTALUM-CONTAINING DEPOSITS FROM PROCESS CHAMBER COMPONENTS
008061KORSP	KOREA	7009437/05	11/25/2002	5/25/2005					METHOD OF CLEANING A COATED PROCESS CHAMBER COMPONENT
008061KORSP02	KOREA	7014433/06	12/19/2003	7/18/2006					CLEANING TANTALUM-CONTAINING DEPOSITS FROM PROCESS CHAMBER COMPONENTS
008061USAP03	US	10/870,716	11/25/2002	6/17/2004					ELECTROCHEMICAL REMOVAL OF TANTALUM-CONTAINING MATERIALS
008061TAIW	TAIWAN	92132955.0	11/25/2002	11/24/2003	283886				METHOD OF CLEANING A COATED PROCESS CHAMBER COMPONENT
008061TAIW02	TAIWAN	93114915.0	11/25/2002	5/26/2004	304612				CLEANING TANTALUM-CONTAINING DEPOSITS FROM PROCESS CHAMBER COMPONENTS
008061USA	US	10/304,535	11/25/2002	11/25/2002	6902628				METHOD OF CLEANING A COATED PROCESS CHAMBER COMPONENT
008061USAP01	US	10/742,604	11/25/2002	12/19/2003	6902627				CLEANING CHAMBER SURFACES TO RECOVER METAL-CONTAINING COMPOUNDS
008931USAC01	US	12/618,693	6/7/2004	11/13/2009					TEXTURED CHAMBER SURFACE□
008931USA	US	10/863,151	6/7/2004	6/7/2004	7618769				TEXTURED CHAMBER SURFACE□
010889EPCX	EP	1965897.0	8/11/2000	2/11/2003					SYSTEM AND METHOD FOR CLEANING SEMICONDUCTOR FABRICATION EQUIPMENT
010889USAD03	US	11/400,125	8/10/2001	4/7/2006					SYSTEM AND METHOD FOR CLEANING SEMICONDUCTOR FABRICATION EQUIPMENT PARTS
010889TAIW	TAIWAN	90119596.0	8/11/2000	8/10/2001	161138				SYSTEM AND METHOD FOR CLEANING SEMICONDUCTOR FABRICATION EQUIPMENT
010889USA	US	09/927,263	8/10/2001	8/10/2001	6810887				SYSTEM AND METHOD FOR CLEANING SEMICONDUCTOR FABRICATION EQUIPMENT